

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims

1. (Canceled).
2. (Currently Amended) The apparatus as claimed in claim 3 [[1]], characterized in that, in the curing device which is connectable to the conveyor belt, a plurality of processing and/or control units are arranged in the transport direction of the conveyor belt, which processing and/or control units carry out simultaneous processing and/or control of the substrates fitted with the semiconductor chips as they are transported.
3. (Currently Amended) An apparatus for applying semiconductor chips to a plurality of substrates, wherein at an adhesive application device adhesive is applied to the substrate at predefined substrate positions, at a fitting device the substrate is fitted in a defined fitting time with the semiconductor chips at the substrate positions, and in a curing device the adhesive is cured, characterized in that at least the curing device having a process time substantially exceeding the fitting time is connectable by a clamping device to a conveyor belt which transports the substrates along the adhesive application and fitting devices, and wherein the curing device is movable in the transport direction, at a transport speed of the conveyor belt, by a lifting device,

~~The apparatus as claimed in claim 2, characterized by~~

further comprising a timer device for setting a time duration which corresponds to the sum of a processing and/or control time of a processing and/or control unit and a time period which is required to return the moved curing device and/or the further device to a starting position in a direction counter to the transport direction.

4. (Currently Amended) An apparatus for applying semiconductor chips to a plurality of substrates, wherein at an adhesive application device adhesive is applied to the substrate at predefined substrate positions, at a fitting device the substrate is fitted in a defined fitting time with the semiconductor chips at the substrate positions, and in a curing device the adhesive is cured, characterized in that at least the curing device having a process time substantially exceeding the fitting time is connectable by a clamping device to a conveyor belt which transports the substrates along the adhesive application and fitting devices, and wherein the curing device is movable in the transport direction, at a transport speed of the conveyor belt, by a lifting device.

~~The apparatus as claimed in claim 3,~~ characterized in that arranged in the curing device ~~and/or said further device~~ are the same number of processing and/or control units as the number of substrates moving in the transport direction which can be fitted by the fitting device at a predefined fitting speed within the processing and/or control time.

5. (Currently Amended) The apparatus as claimed in claim 3 ~~[[1]]~~, characterized in that the movable curing device comprises a thermode array arranged above the conveyor belt, said thermode array comprising a plurality of thermodes assigned to the substrate positions of the substrates, and at least one heating plate arranged below the conveyor belt.
6. (Previously Presented) The apparatus as claimed in claim 5, characterized in that the thermode array and the heating plate are movable by a slide device in a direction perpendicular to the plane of the conveyor belt in such a way that, with the clamping device closed, they are movable toward the conveyor belt and away from the conveyor belt.
7. (Canceled).

8. (Currently Amended) The apparatus as claimed in claim 3 [[1]], characterized in that the lifting device is connected to a conveyor belt drive for moving the conveyor belt in a step-wise manner in the transport direction.
9. (Currently Amended) An apparatus for applying semiconductor chips to a plurality of substrates, wherein at an adhesive application device adhesive is applied to the substrate at predefined substrate positions, at a fitting device the substrate is fitted in a defined fitting time with the semiconductor chips at the substrate positions, and in a curing device the adhesive is cured, characterized in that at least the curing device having a process time substantially exceeding the fitting time is connectable by a clamping device to a conveyor belt which transports the substrates along the adhesive application and fitting devices, and wherein the curing device is movable in the transport direction, at a transport speed of the conveyor belt, by a lifting device,

~~The apparatus as claimed in claim 3,~~ characterized by a further clamping device, fixed to the apparatus, for keeping said conveyor belt stationary while the moved curing device is being returned in the direction counter to the transport direction.

10. (Previously Presented) A method for applying semiconductor chips to a plurality of substrates, wherein at an adhesive application device adhesive is applied to the substrate at predefined substrate positions, at a fitting device the substrate is fitted in a defined fitting time with the semiconductor chips at the substrate positions, and in a curing device the adhesive is cured, characterized by the following steps:
- connecting at least the curing device having a process time substantially exceeding the fitting time to a conveyor belt which transports the substrates along the adhesive application and fitting devices, by closing a first clamping device;
 - opening a second clamping device, fixed to the apparatus, so as to release the conveyor belt moving in the transport direction;

- moving processing and/or control units arranged in the curing into a closed position in a direction perpendicular to the plane of the conveyor belt;
 - moving the curing device at a transport speed of the conveyor belt in the transport direction during a simultaneous processing and/or control of a plurality of substrates fitted with the semiconductor chips for a predefined processing and/or control time by means of the processing and/or control units;
 - moving the processing and/or control units into an open position away from the plane of the conveyor belt following expiry of the processing and/or control time;
 - closing the second clamping device which is fixed to the apparatus;
 - opening the first clamping device;
 - returning the curing device to a starting position in a direction counter to the transport direction.
11. (Previously Presented) The method as claimed in claim 10, characterized in that the step of moving the processing and/or control units into an open position can be carried out independently of a movement of the conveyor belt in the transport direction.
12. (Previously Presented) The method as claimed in claim 10, characterized in that the transport speed corresponds to a fitting speed at which the substrates on the conveyor belt are fitted, said conveyor belt moving in a step-wise manner.
13. (Previously Presented) The method as claimed in claim 11, characterized in that the transport speed corresponds to a fitting speed at which the substrates on the conveyor belt are fitted, said conveyor belt moving in a step-wise manner.
14. (Canceled).

15. (Currently Amended) The apparatus as claimed in claim 3 [[14]], characterized in that arranged in the curing device ~~and/or said further device~~ are the same number of processing and/or control units as the number of substrates moving in the transport direction which can be fitted by the fitting device at a predefined fitting speed within the processing and/or control time.
16. (Currently Amended) The apparatus as claimed in claim 3 [[14]], characterized by a further clamping device, fixed to the apparatus, for keeping said conveyor belt stationary while the moved curing device is being returned in the direction counter to the transport direction.
17. (Previously Presented) An apparatus for applying semiconductor chips to a plurality of substrates, wherein at an adhesive application device adhesive is applied to the substrate at predefined substrate positions, at a fitting device the substrate is fitted in a defined fitting time with the semiconductor chips at the substrate positions, and in a curing device the adhesive is cured, characterized in that at least the curing device having a process time substantially exceeding the fitting time is connectable by a clamping device to a conveyor belt which transports the substrates along the adhesive application and fitting devices, and wherein the curing device is movable in the transport direction, at a transport speed of the conveyor belt, by a lifting device; wherein the clamping device comprises at least two clamping jaw units which are preferably arranged at end regions of the movable curing device, the upper and lower clamping jaws of which are guidable toward the conveyor belt from above and below.
18. (New) The apparatus as claimed in claim 4, characterized in that, in the curing device which is connectable to the conveyor belt, a plurality of processing and/or control units are arranged in the transport direction of the conveyor belt, which processing and/or control units carry out simultaneous processing and/or control of the substrates fitted with the semiconductor chips as they are transported.

19. (New) The apparatus as claimed in claim 17, characterized in that, in the curing device which is connectable to the conveyor belt, a plurality of processing and/or control units are arranged in the transport direction of the conveyor belt, which processing and/or control units carry out simultaneous processing and/or control of the substrates fitted with the semiconductor chips as they are transported.
20. (New) The apparatus as claimed in claim 9, characterized in that, in the curing device which is connectable to the conveyor belt, a plurality of processing and/or control units are arranged in the transport direction of the conveyor belt, which processing and/or control units carry out simultaneous processing and/or control of the substrates fitted with the semiconductor chips as they are transported.